

Docket No.: 27-035.D1

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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AMSB

In re Application of:	John Briar	:	Confirmation No.:	2274
Serial No.:	10/693,217	:	Art Unit:	2811
Filed:	10/24/2003	:	Examiner:	Douglas W. Owens
For:	FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE STRUCTURE			

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AMENDMENT AFTER FINAL REJECTION
UNDER 37 C.F.R. §1.116

Sir:

The following is a resubmission of the Amendment and Remarks previously filed July 24, 2005, in which edit marks in the claims were inadvertently suppressed/turned off during printing of the document.

The following Amendment and Remarks are submitted under 37 C.F.R. §1.116 in response to the Office Action mailed May 23, 2005, and Notice of Non-Compliant Amendment mailed August 15, 2005, following the amendment format set forth under 37 CFR §1.121. After this introductory section, there are Amendments to the Claims and then Remarks, each starting on a separate page.

Amendments to the Claims consist of deletion of claims 16, 17, and 21, amendments for claims 12, 14, and 18, and new claims 23-28, which are incorporated in a complete listing of the claims.

Reconsideration of the rejections is respectfully submitted